

AMENDMENTS TO THE SPECIFICATION:

Please add the following headings to the specification at page 1, line 3:

BACKGROUND OF THE INVENTION

1. Field of the Invention

Please add the following heading to the specification at page 1, line 8:

2. Description of Related Art

Please add the following heading to the specification at page 1, line 27:

BRIEF SUMMARY OF THE INVENTION

Please amend the Abstract of the Disclosure as follows:

~~The invention relates to processes~~ Processes for producing copy protection for an integrated circuit are provided. To avoid unauthorized copying of an integrated circuit, ~~it is an object of the invention to provide~~ an effective and reliable copy protection are provided. ~~The invention proposes a process comprising~~ includes the steps of providing a substrate (1) ~~which~~ that has semiconductor structures (2) on at least a first side (1a) of the substrate (1), providing a material (23) for coating the substrate (1), and coating the substrate (1) with a copy-protect layer (4). ~~It has proven particularly advantageous for~~ In one embodiment, the copy-protect layer (4) to be is produced by applying a silicate glass by evaporation coating. Thus, ~~since this means that~~ an etching process ~~which~~ that dissolves the copy-protect layer also attacks the substrate (1), ~~in such a manner so~~ that the semiconductor structures (2) are at least partially destroyed.